Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP ENVY 14 - 14-1000 to 14-1099

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, Audio /B, Wireless /B, Battery /B, ODD /B</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Primary battery, RTC battery</td>
<td>3</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Motor-screw-driver &quot;+&quot;</td>
<td>Cross head of screwdriver</td>
</tr>
<tr>
<td>Description #2 Motor-screw-driver &quot;-&quot;</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Slide latch on big system door and release small battery door.
2. Remove 5 screws on big system door and slide to remove big system door.
3. Remove DDR memory module.
4. Remove black mylar on Charger board.
5. Release right side battery latch.
6. Slide left battery latch and pull up main battery.
7. Remove 4 screws on 4 corner of HDD. Pull out HDD.
8. Remove 4 screws in battery and HDD bay.
9. Release touch pad FFC.
11. Release WLAN antenna from WLAN module.
12. Remove 2 screws on WLAN module. Remove WLAN module.
14. Remove 4 screws from 4 corners of battery and HDD bay.
15. Remove 4 screws under big system door.
16. Remove antennas from bottom case.
17. Flip unit up and remove top case.
18. Remove aluminum foil on touch pad FFC then remove touch pad FFC.
19. Remove keyboard light FFC.
20. Remove keyboard FFC.
21. Remove power cable from system.
22. Remove DC jack cable.
23. Remove 4 screws then remove ODD drive.
24. Remove ODD FFC from ODD drive.
25. Pull out antenna from bottom case routing hole.
26. Remove 4 screws from hinges.
27. Release and remove LCM cable.
28. Flip unit to bottom up.
29. Remove mylar on 2nd battery connector.
30. Remove 5 screws and remove charger board.
31. Remove charger board and release charger board FFC.
32. Flip unit up.
33. Remove USB/B FFC
34. Remove SIM/B FFC
35. Remove 2 screws on mother board.
36. Remove 3 screws on mother board.
37. Remove mother board from system.
39. Remove 1 screw then remove SIM/B.
40. Remove 4 screws then remove speaker.
41. Remove bluetooth from bottom case.
42. Remove bluetooth cable.
43. Put main board on support fixture and release FAN cables.
44. Remove 9 screws of thermal module and remove thermal module.
45. Untight screw on CPU socket then remove CPU.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
[Attached in separated file]